



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



SURFBOARDS®



THE BREADBOARDING MEDIUM FOR **SURFACE MOUNT™**

33000 SERIES APPLICATION SPECIFIC ADAPTERS

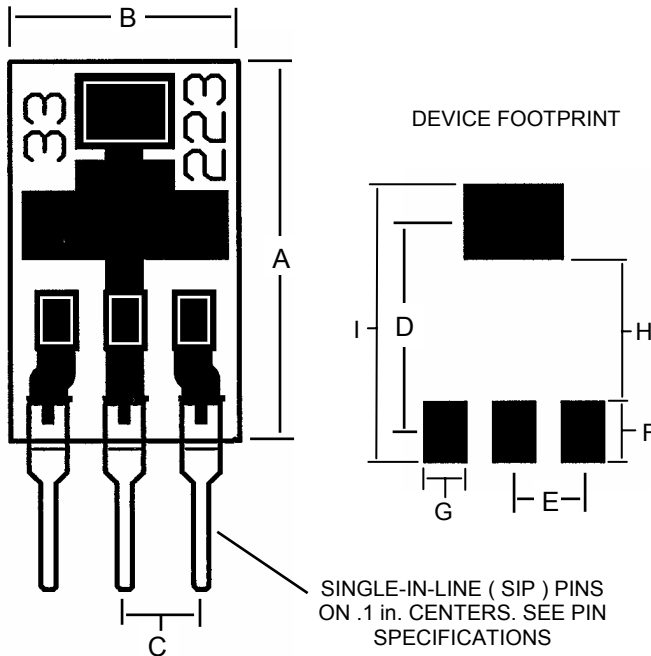
IDS33223

REV 1-2012

MODEL 33223

FOR SOT-223 SC-73

SURFACE MOUNT DEVICES



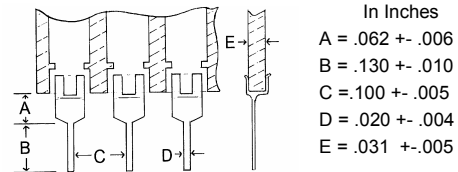
PINS ON .100 in. CENTERS OFFER COMPATIBILITY WITH BREADBOARDS AND SOCKETS.

FOR PROTOTYPING, DEVICE EVALUATION OR TEST, OR SMD TO THROUGH HOLE CONVERSION.

NOTE: CIRCUIT TRACE FOILS AND OUTPUT PINS MAY NOT BE SUITABLE FOR OPERATION AT HIGHER CURRENT LEVELS. EXTREME TEMPERATURE RISE MAY RESULT IN BOARD OR PIN FAILURE.

SEE MODEL 33623 FOR HIGHER CURRENT APPLICATIONS USING SOT-223 DEVICES

PIN SPECIFICATIONS / TOLERANCES



In Inches
 A = .062 +/- .006
 B = .130 +/- .010
 C = .100 +/- .005
 D = .020 +/- .004
 E = .031 +/- .005

FIG.	INCHES	MM	NOTE:
A	.500	12.70	BOARD HEIGHT +/- .5mm .020in.
B	.300	7.62	BOARD WIDTH +/- .5mm .020in.
C	.100	2.54	SIP PIN SPACE +/- .20mm .008in.
D	.275	6.98	PAD CENTERLINE
E	.090	2.28	DEVICE LEAD PITCH
F	.080	2.03	PAD LENGTH
G	.055	1.39	PAD WIDTH
H	.185	4.69	GAP
I	.365	9.27	MAX PIN WIDTH



BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +/- .13mm .031in +/- .005 in. Thick G-10 FR-4 Glass Epoxy or equivalent.
CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +/- .5mm .020in.

TOLERANCES: If not noted are +/- 20%. Nominal values are given. Controlling unit is Millimeters. Values rounded to nearest decimal. Slight Variations due to manufacturing process can occur.

Copyright 1997-2012 by Capital Advanced Technologies, Inc. All rights reserved. Surfboards is a registered trademark of Capital Advanced Technologies, Inc. The Breadboarding medium for surface mount, and the Leaf Circuit Logo are trademarks of Capital Advanced Technologies, Inc. All other trademarks are the property of their respective owners. Specifications, availability, and price is subject to change without notice. All information given is believed to be accurate but is not guaranteed. The user of information given or products represented by such information is responsible for determining the suitability of said information or products for a given purpose. No inducement is intended or permission granted for infringement of any patent or unauthorized use of any intellectual property of Capital Advanced Technologies or others.

CAPITAL ADVANCED TECHNOLOGIES, INC.

CAROL STREAM, ILLINOIS. USA.

PHONE 630-690-1696

WWW.CapitalAdvanced.Com

FAX 630-690-2498